

REMARKS

Applicant has reviewed and considered the Office Action mailed on September 23, 2002, and the references cited therewith.

Claims 1, 3, 34, and 36 are amended, and claims 2 and 35 are canceled without prejudice or disclaimer. Claims 42 and 43 are added. Claims 1, 3-6, 32-34, and 36-43 are now pending in this application. No new matter is added by these amendments. Support for the amendments is found, for example, in Fig. 1, which shows two fans with alternative air flow arrows, and page 8, lines 14-21. Applicant respectfully requests reconsideration and allowance of all claims in view of the amendments above and the remarks that follow.

§102 Rejection of the Claims

Claims 1-3, 5-6, 34-36, and 38-39 were rejected under 35 USC § 102(e) as being anticipated by Papa et al. (US 6,175,490 B1). Applicant does not admit that Papa is prior art and reserves the right to swear behind it at a later date. Nevertheless, applicant respectfully submits that the claims are patentable over Papa because Papa does not teach or suggest all the elements of the claims for the reasons argued below.

Claim 1 recites: "a passage; a first fan suitable for passing air through the passage; ... an alternate passage configured to provide an air flow path to the isolation assembly; and a second fan suitable for passing air through the alternate passage." In contrast, Papa describes two fans 566A and 566B that are connected serially, so they blow air in the same path. *Papa at Fig. 6.* Thus, Papa does not teach or suggest first and second fans that pass air through a passage and an alternate passage, respectively, as recited in claim 1.

Claim 34 contains similar elements as argued above for claim 1 and is patentable over Papa for similar reasons. Claims 3, 5-6, 36, and 38-39 are dependent on claims 1 and 34, respectively, and are patentable over Papa for the reasons argued above.

§103 Rejection of the Claims

Claims 4, 32-33, 37, and 40-41 were rejected under 35 USC § 103(a) as being

unpatentable over Papa in view of Behl (US 6,185,097 B1). Claims 4, 32-33, 37, and 40-41 are dependent on claims 1 and 34, respectively, and are patentable over Papa for the reasons argued above.

Behl also does not teach or suggest "a passage; a first fan suitable for passing air through the passage; ... an alternate passage configured to provide an air flow path to the isolation assembly; and a second fan suitable for passing air through the alternate passage," as recited in claim 1. Behl shows its memory storage device coolers 16 and its fans 30 operating in the same conduit. *Behl at Fig. 2, 3, 6, 7, 9, 10, and 12; column 2, line 19; column 4, lines 56-58; and column 5, lines 27-28.* Hence, Behl also does not teach or suggest first and second fans that pass air through a passage and an alternate passage, as recited in claim 1, on which claims 4 and 32-33 depend.

Claim 34, on which claims 37 and 40-41 depend, contains similar elements as argued above for claim 1 and is patentable over Behl for similar reasons.

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney (612-371-2103) to facilitate prosecution of this application.

AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116 - EXPEDITED PROCEDURE

Serial Number: 10/034,110

Filing Date: December 26, 2001

Title: CPU FAN ASSEMBLY

Page 6

Dkt: 450.232US2

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 50-0439.

Respectfully submitted,

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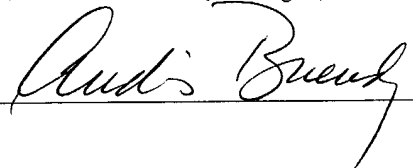
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Box AF, Commissioner of Patents, Washington, D.C. 20231, on this 23 day of December, 2002.

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CLEAN VERSION OF PENDING CLAIMS

1. (Three Times Amended) A cooling assembly for at least one board, the at least one board suitable for accepting a plurality of components including a first component, the cooling assembly comprising:
- a passage;
 - a first fan suitable for passing air through the passage;
 - an isolation assembly for generally enclosing heat generated from the first component, wherein the first component is enclosed within the isolation assembly, the isolation assembly in communication with the passage, wherein the isolation assembly is removably attachable to a computer case without opening the computer case, and wherein the passage is separate from another heat-sensitive component within the computer case;
 - an alternate passage configured to provide an air flow path to the isolation assembly; and
 - a second fan suitable for passing air through the alternate passage.
3. (Amended) The cooling assembly of claim 1, wherein the alternate passage includes a conduit in communication with the isolation assembly.
4. (Unchanged) The cooling assembly of claim 1, and further comprising a heat sink operably coupled to the first component.
5. (Unchanged) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.
6. (Unchanged) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

32. The cooling assembly of claim 4, wherein the heat sink comprises a passive heat sink.

33. The cooling assembly of claim 1, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

34. (Amended) A cooling assembly for at least one board, the at least one board suitable for accepting a plurality of components including a first component, the cooling assembly comprising:

a passage;

a first fan suitable for passing air through the passage;

an isolation assembly for generally enclosing heat generated from the first component, wherein the first component is enclosed within the isolation assembly, the isolation assembly in communication with the passage, and wherein the passage is separate from another heat-sensitive component within a computer case;

an alternate passage configured to provide an air flow path to the isolation assembly; and

a second fan suitable for passing air through the alternate passage.

36. (Amended) The cooling assembly of claim 34, wherein the alternate passage includes a conduit in communication with the isolation assembly.

37. The cooling assembly of claim 34, and further comprising a heat sink operably coupled to the first component.

38. The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

39. The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

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Page 9

Dkt: 450.232US2

Card
40. The cooling assembly of claim 37, wherein the heat sink comprises a passive heat sink.

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41. The cooling assembly of claim 34, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

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42. (New) The cooling assembly of claim 1, wherein the first component comprises a processor.

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43. (New) The cooling assembly of claim 34, wherein the first component comprises a processor.